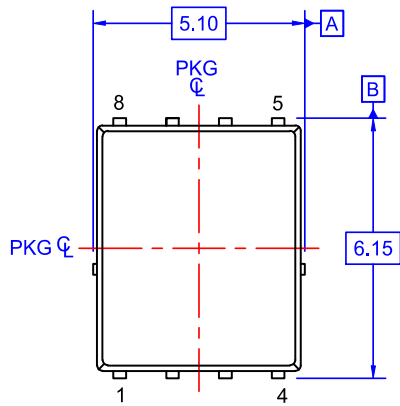


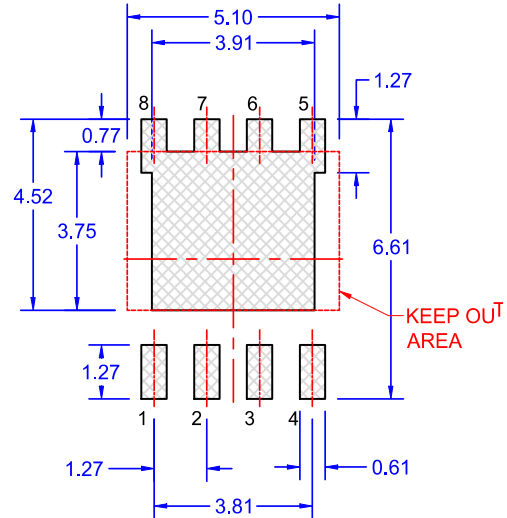
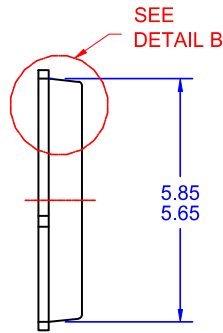


**PQFN8 5X6, 1.27P**  
**CASE 483AE**  
**ISSUE A**

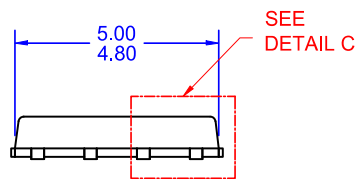
DATE 27 SEP 2017



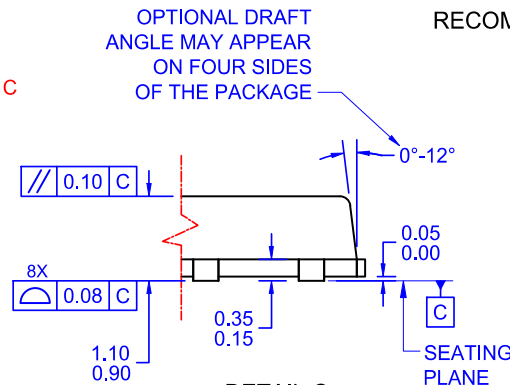
TOP VIEW



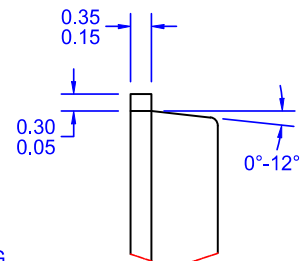
LAND PATTERN RECOMMENDATION



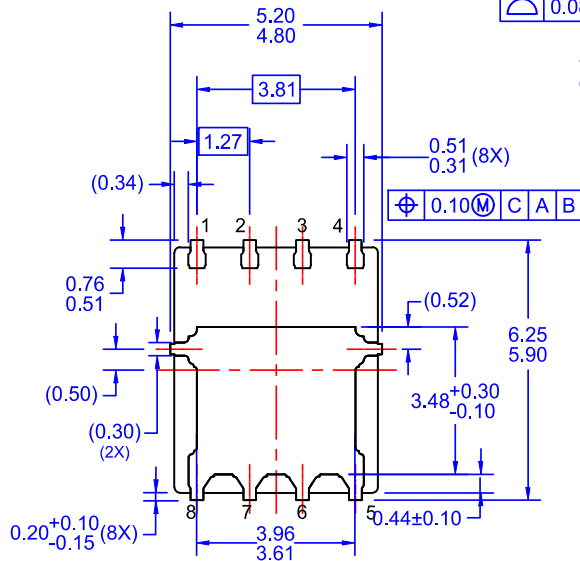
SIDE VIEW



DETAIL C  
 SCALE: 2:1



DETAIL B  
 SCALE: 2:1



NOTES: UNLESS OTHERWISE SPECIFIED

- A. PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. AA,.
- B. DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- E. IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.

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<b>DESCRIPTION:</b>	<b>PQFN8 5X6, 1.27P</b>	<b>PAGE 1 OF 1</b>

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